

FDMC8678S

N-Channel Power Trench® SyncFET™ 30V, 18A, 5.2mΩ

Features

- Max $r_{DS(on)}$ = 5.2mΩ at $V_{GS} = 10V$, $I_D = 15A$
- Max $r_{DS(on)}$ = 8.7mΩ at $V_{GS} = 4.5V$, $I_D = 12A$
- Advanced Package and Silicon combination for low $r_{DS(on)}$ and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- RoHS Compliant



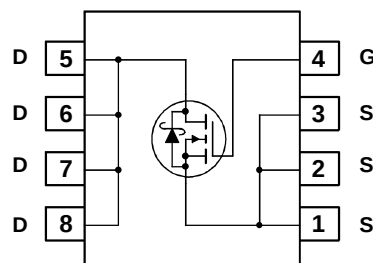
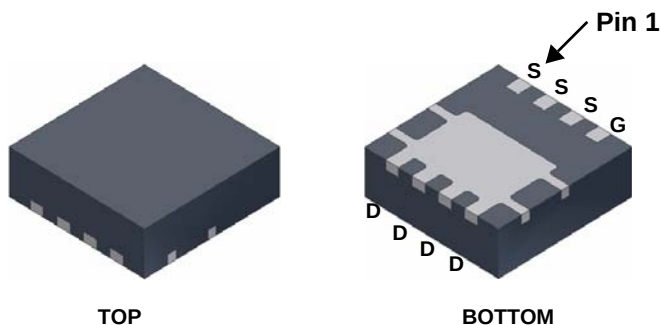
General Description

The FDMC8678S has been designed to minimize losses in power conversion applications. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{DS(on)}$ while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

Applications

Synchronous Rectifier for DC/DC Converters

- Notebook Vcore/ GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	18	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	66	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	15	
	-Pulsed	60	
E_{AS}	Single Pulse Avalanche Energy (Note 3)	181	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	41	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	2.3	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
8678S	FDMC8678S	Power 33	13"	12 mm	3000 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{mA}$, $V_{GS} = 0\text{V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{mA}$, referenced to 25°C		38		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}$, $V_{DS} = 24\text{V}$,			500	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$			± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1\text{mA}$	1	1.9	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 1\text{mA}$, referenced to 25°C		-3.7		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}$, $I_D = 15\text{A}$		4.3	5.2	m Ω
		$V_{GS} = 4.5\text{V}$, $I_D = 12\text{A}$		6.3	8.7	
		$V_{GS} = 10\text{V}$, $I_D = 15\text{A}$, $T_J = 125^\circ\text{C}$		6	10	
g_{FS}	Forward Transconductance	$V_{DD} = 10\text{V}$, $I_D = 15\text{A}$		55		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 15\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$		1560	2075	pF
C_{oss}	Output Capacitance			810	1080	pF
C_{rss}	Reverse Transfer Capacitance			90	135	pF
R_g	Gate Resistance	$f = 1\text{MHz}$		0.8		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{V}$, $I_D = 15\text{A}$, $V_{GS} = 10\text{V}$, $R_{GEN} = 6\Omega$		11	20	ns
t_r	Rise Time			3	10	ns
$t_{d(off)}$	Turn-Off Delay Time			24	39	ns
t_f	Fall Time			2	10	ns
Q_g	Total Gate Charge	$V_{GS} = 0\text{V}$ to 10V	$V_{DD} = 15\text{V}$, $I_D = 15\text{A}$	24	34	nC
Q_g	Total Gate Charge	$V_{GS} = 0\text{V}$ to 4.5V		11	16	nC
Q_{gs}	Gate to Source Charge			4.7		nC
Q_{gd}	Gate to Drain "Miller" Charge			2.8		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_S = 3\text{A}$ (Note 2)		0.5	0.7	V
t_{rr}	Reverse Recovery Time	$I_F = 15\text{A}$, $di/dt = 300\text{A}/\mu\text{s}$		31	51	ns
Q_{rr}	Reverse Recovery Charge			33	51	nC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1in^2 pad 2 oz copper pad on a $1.5 \times 1.5\text{in.}$ board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 53°C/W when mounted on a 1in^2 pad of 2 oz copper



b. 125°C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width $< 300\mu\text{s}$, Duty cycle $< 2.0\%$.

3. Starting $T_J = 25^\circ\text{C}$; N-ch: $L = 3\text{mH}$, $I_{AS} = 11\text{A}$, $V_{DD} = 30\text{V}$, $V_{GS} = 10\text{V}$

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

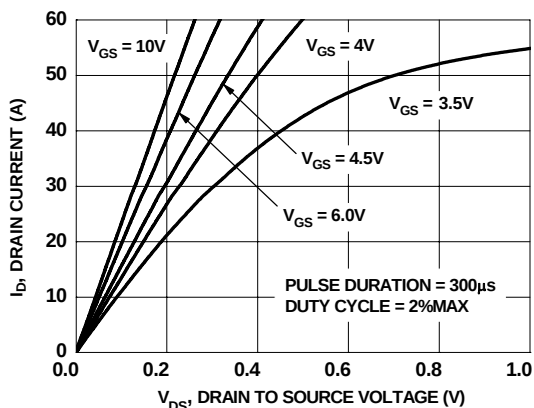


Figure 1. On-Region Characteristics

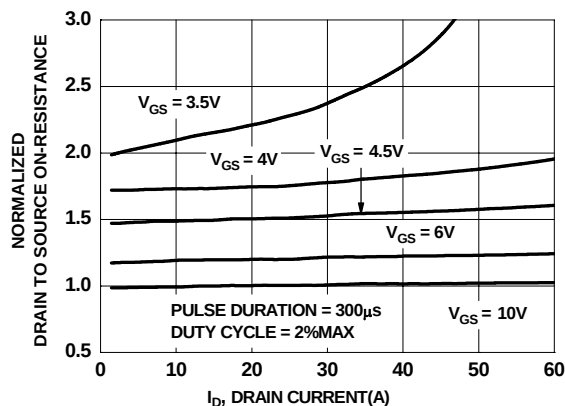


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

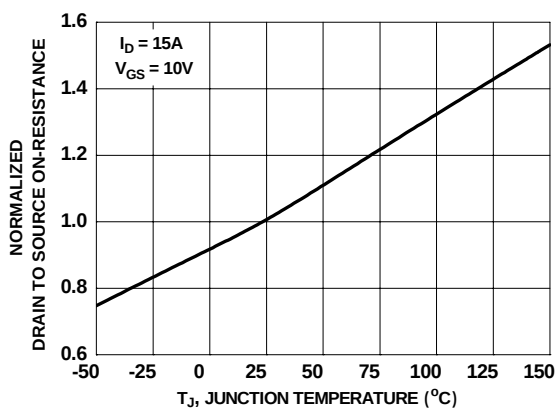


Figure 3. Normalized On-Resistance vs Junction Temperature

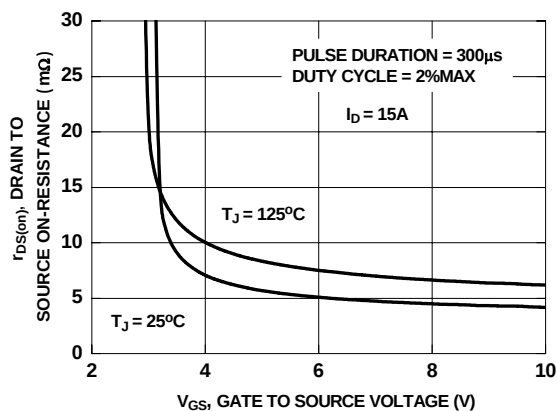


Figure 4. On-Resistance vs Gate to Source Voltage

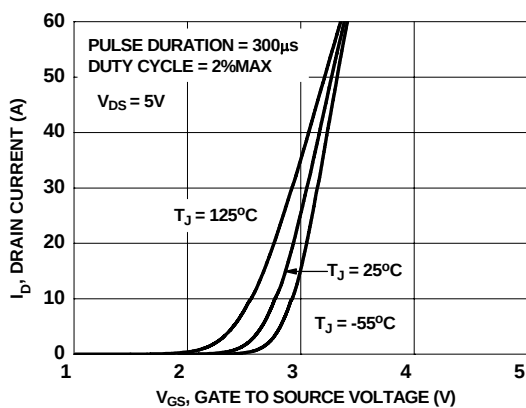


Figure 5. Transfer Characteristics

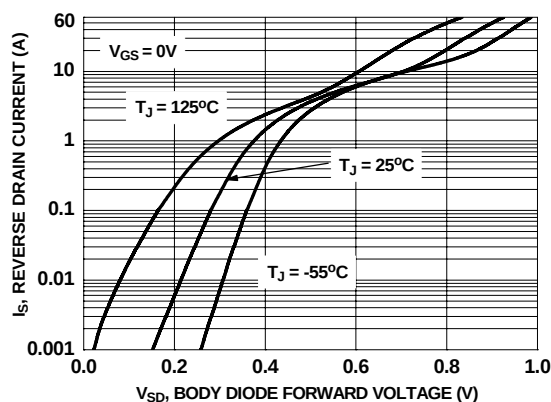


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

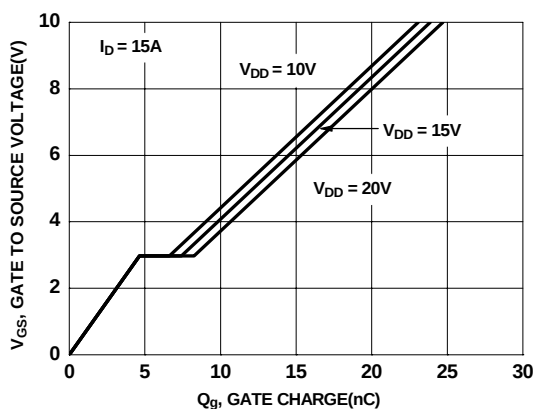


Figure 7. Gate Charge Characteristics

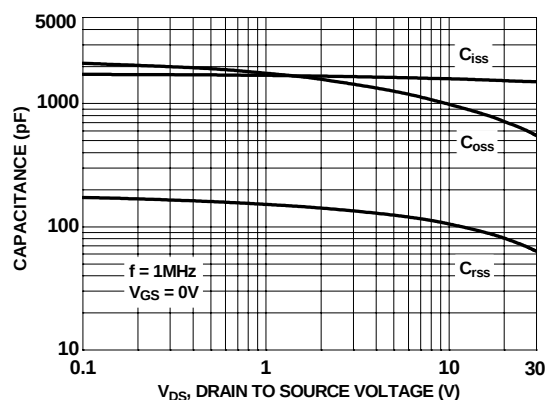


Figure 8. Capacitance vs Drain to Source Voltage

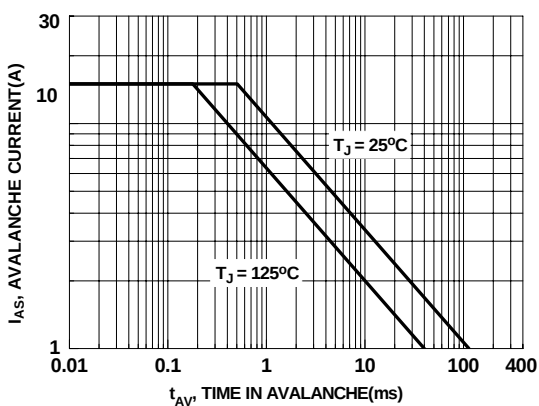


Figure 9. Unclamped Inductive Switching Capability

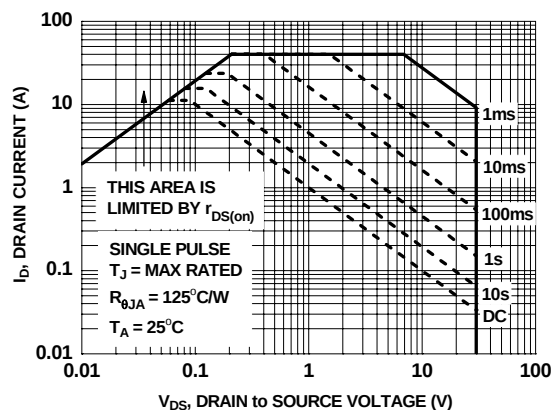


Figure 10. Forward Bias Safe Operating Area

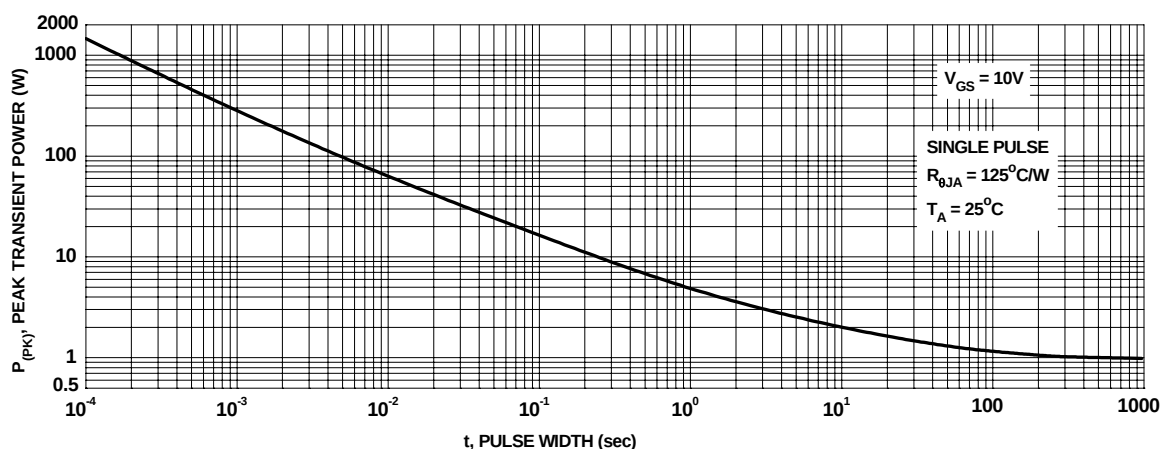
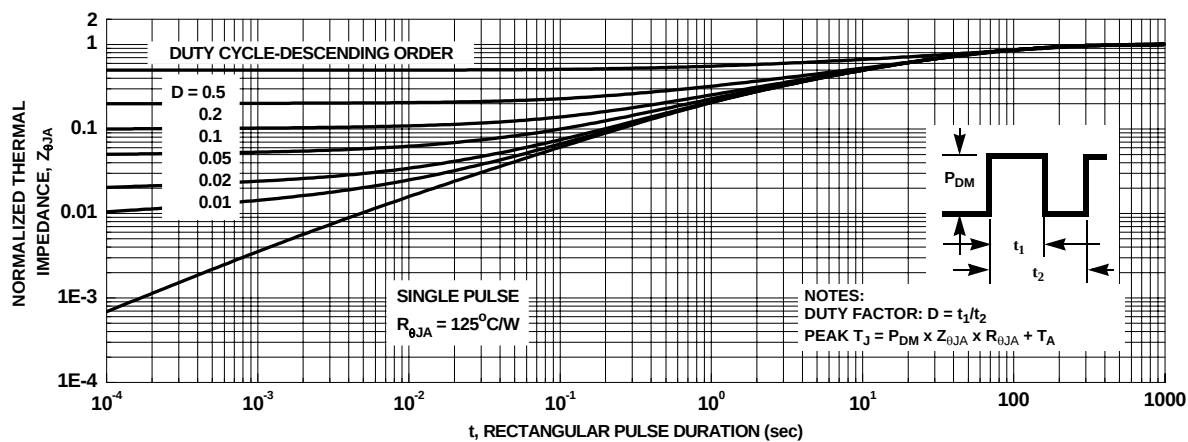


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted



Typical Characteristics (continued)

SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench[®] MoSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMC8678S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

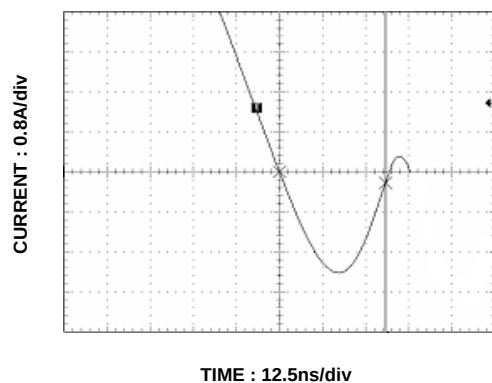


Figure 13. SyncFET body diode reverse recovery characteristic

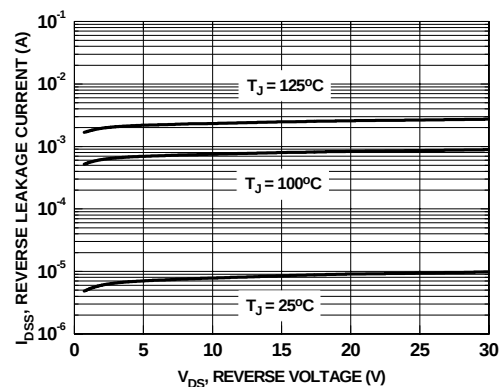
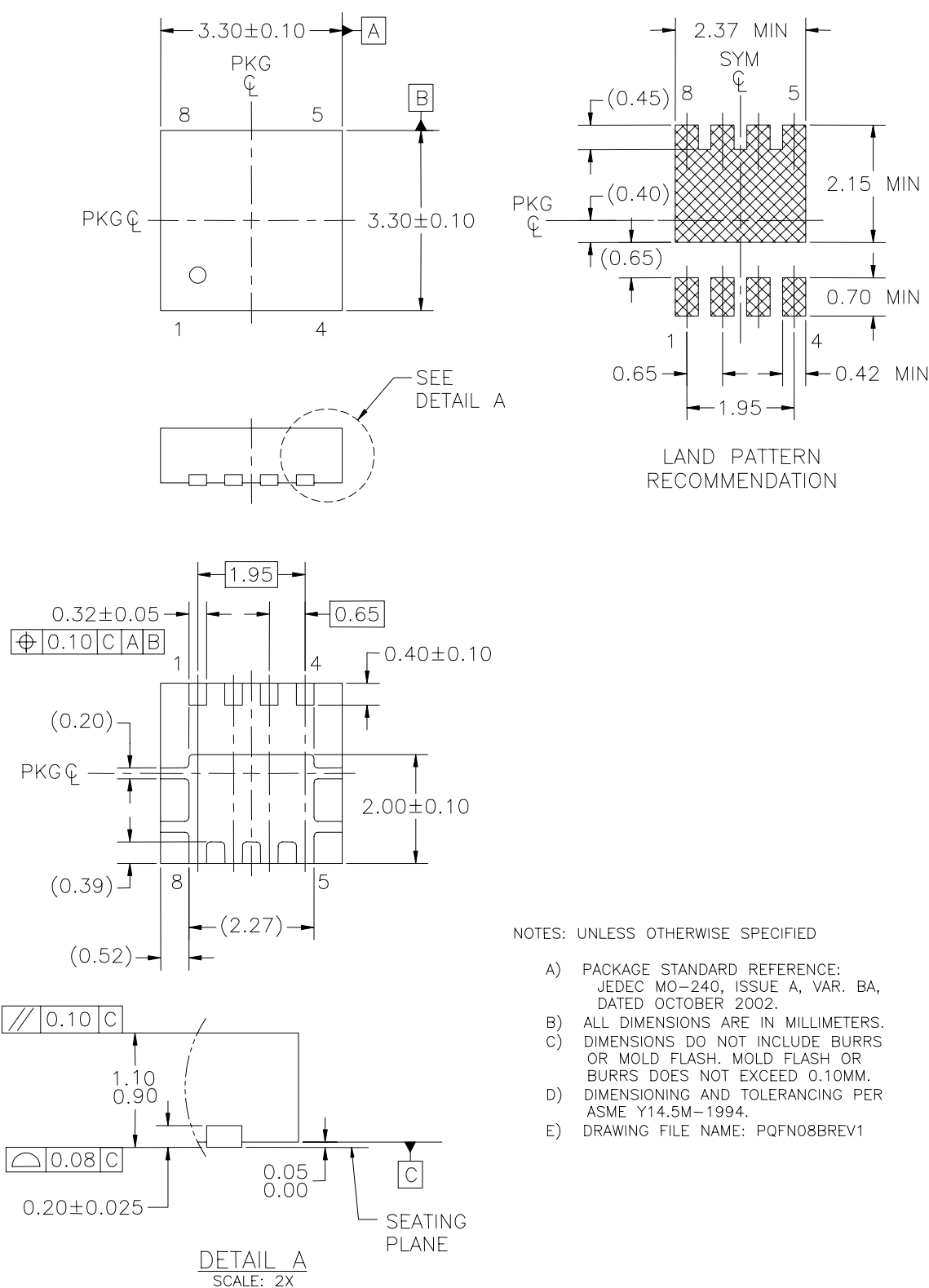


Figure 14. SyncFET body diode reverse leakage versus drain-source voltage

Dimensional Outline and Pad Layout



PQFN08BREV1

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